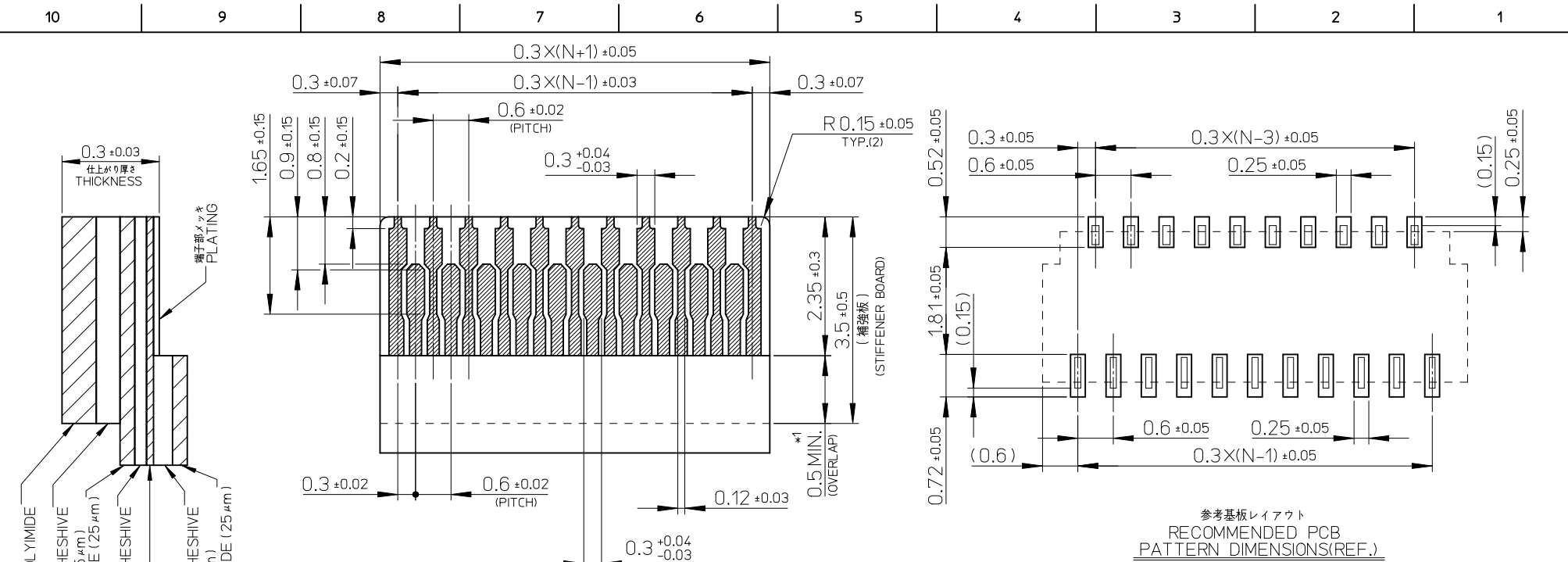


注記 NOTES

- 使用材料 MATERIAL  
 ハウジング: 液晶ポリマー(LCP)、ナチュラル(白色系)、ガラス充填、UL94V-0  
 奇数端子: 燐青銅、ニッケル下地、金メッキ  
 偶数端子: 燐青銅、ニッケル下地、金メッキ  
 HOUSING: LIQUID CRYSTAL POLYMER(LCP), NATURAL(WHITE)  
 GLASS FILEED, UL94V-0  
 ODD TERMINAL: PHOSPHOR BRONZE, Gold OVER Nickel PLATING  
 EVEN TERMINAL: PHOSPHOR BRONZE, Gold OVER Nickel PLATING
- めっき仕様 PLATING  
 ターミナル TERMINAL  
 接点部: 金メッキ 0.1μm以上  
 テール部: 金メッキ  
 下地: ニッケルメッキ 1.0μm以上  
 CONTACT AREA: GOLD PLATING 0.1μm MINIMUM  
 TAIL AREA: GOLD PLATING  
 UNDER PLATING: NICKEL PLATING 1.0μm MINIMUM
- 端子のコプラナリティーは 0.1 以下とする。  
 COPLANALITY OF SOLDER TAILS: 0.1MAX.
- ELV及びRoHS適合品  
 ELV AND RoHS COMPLIANT
- 一般公差: ±0.3  
 GENERAL TOLERANCE: ±0.3

6.0	4.8	5.4	6.6	504281-1900	19
5.4	4.2	4.8	6.0	504281-1700	17
4.2	3.0	3.6	4.8	504281-1300	13
3.6	2.4	3.0	4.2	504281-1100	11
D	C	B	A	EMBOSSED PACKAGE	極数
				オーダー番号	ORDER NO.
					CIRCUIT

RELEASED EC NO.: J2014-0037 DRWN: SKUROSE 2014/04/28 CHKD: HIJIMA 2014/04/28 APPR: YNOGAWA 2014/05/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER ±0.2		DRAWN BY NNISHI		DATE 2012/07/17		TITLE 0.3 FPC CONN. NON-ZIF TYPE HGT=1.0MM			
	10 OVER 30 UNDER ±0.25		CHECKED BY HIJIMA		DATE 2012/07/17					
	30 OVER ±0.3		APPROVED BY YNOGAWA		DATE 2014/05/07					
	ANGULAR ±1 °		MATERIAL NO.		SEE CHART		DOCUMENT NO. SD-504281-001		SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



補強板: ポリイミド  
 STIFFENER BOARD: POLYIMIDE  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 ベースフィルム: ポリイミド (25µm)  
 BASE FILM: POLYIMIDE (25µm)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 導体部: 銅箔 (35µm)  
 COPPER FOIL (35µm)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 カバーレイ: ポリイミド (25µm)  
 COVER FILM: POLYIMIDE (25µm)

FPC 構成推奨仕様  
 STRUCTURE OF FPC

適合するFPC推奨寸法 (参考)  
 APPLICABLE FPC  
 PATTERN DIMENSIONS(REF.)  
 (端子仕上がり厚さ: 0.3±0.03)  
 (THICKNESS: 0.3±0.03)

参考基板レイアウト  
 RECOMMENDED PCB  
 PATTERN DIMENSIONS(REF.)

推奨ペースト厚: 100µm  
 推奨マスク開口率: 80%  
 RECOMMEND SCREEN THICKNESS: 100µm  
 RECOMMEND SCREEN OPEN RATIO: 80%

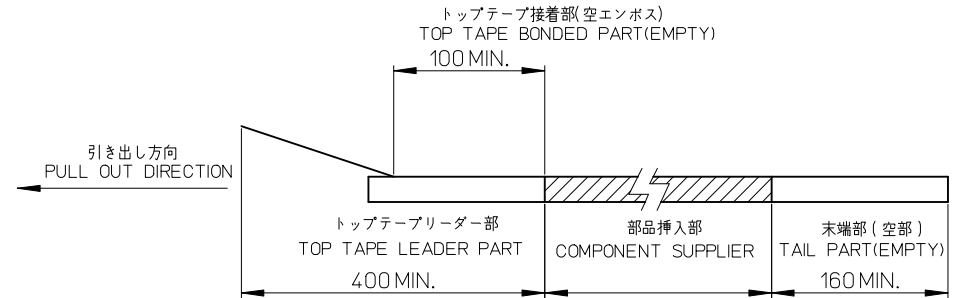
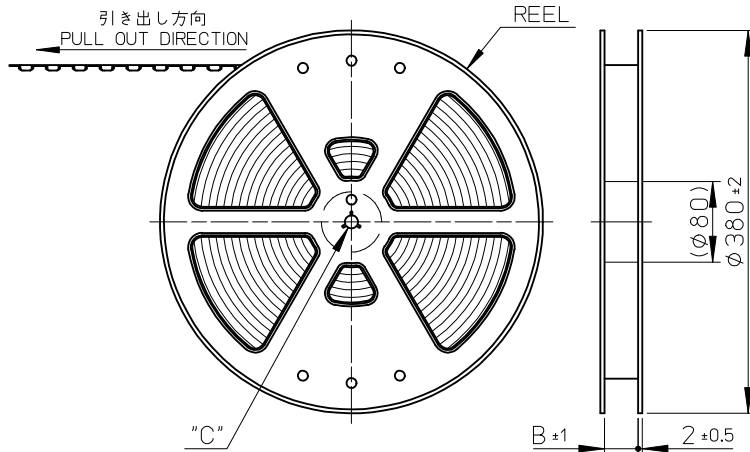
・FPCについて (ABOUT FPC)  
 抜き方向は、導体側から補強板側を推奨します。  
 補強板材質はポリイミド、接着剤は熱硬化接着剤を推奨します。  
 尚、接着剤の接点部への付着は同通不良の原因となりますので、  
 染み出しが無い様お願いします。  
 RECOMMENDED PUNCHER DIRECTION:  
 FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE  
 RECOMMENDED MATERIAL:  
 STIFFENER BOARD: POLYIMIDE  
 BONDING AGENT: THERMOSETTING AGENT  
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON  
 ADHEREND BECAUSE THERE IS A POSSIBILITY THAT  
 THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY

・FPCパターンメッキ仕様 (FPC PATTERN PLATING)  
 金メッキ: 0.1µm以上  
 下地ニッケルメッキ: 2~6µm  
 GOLD PLATING: 0.1µm MINIMUM  
 NICKEL UNDER PLATING: 2~6µm  
 \*1 補強板長さが図面通り確保できない場合は、カバーレイと  
 補強板のオーバーラップ寸法を0.5mm以上として下さい。  
 WHEN STIFFENER BOARD DIMENSION CAN NOT  
 SECURE AS DRAWING, PLEASE GIVE THE OVERLAP  
 SIZE OF COVER FILM AND STIFFENER BOARD AS 0.5mm MINIMUM

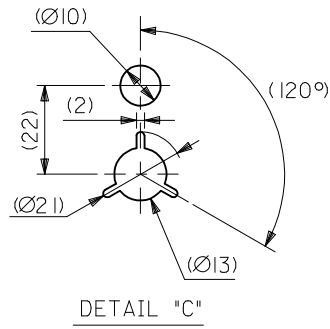
SEE SHEET 1 OF 2 EC NO: J2014-0037 DRWN: SKUROSE 2014/04/28 CHKD: HIJIMA 2014/04/28 APPR: YNOGAWA 2014/05/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
			MM ONLY	15:1	METRIC		
	10 UNDER	+0.2	DRAWN BY	DATE	TITLE		
	10 OVER	±0.25	HIJIMA	2012/07/17	0.3 FPC CONN. NON-ZIF TYPE HGT=1.0MM		
30 OVER	±0.3	YNOGAWA	2014/05/07	molex			
0	ANGULAR ±1 °	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET 1		SD-504281-001		2 OF 2	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

注記 NOTES

- 製品詳細寸法については図面SD-504281-001を参照下さい。  
CONNECTOR DETAILED DIMENSIONS, REFER TO SD-504281-001.
- 梱包数量: 5000個/リール  
NUMBER OF CONNECTORS : 5000PCS / REEL
- リードテープ長さ  
LEAD TAPE LENGTH

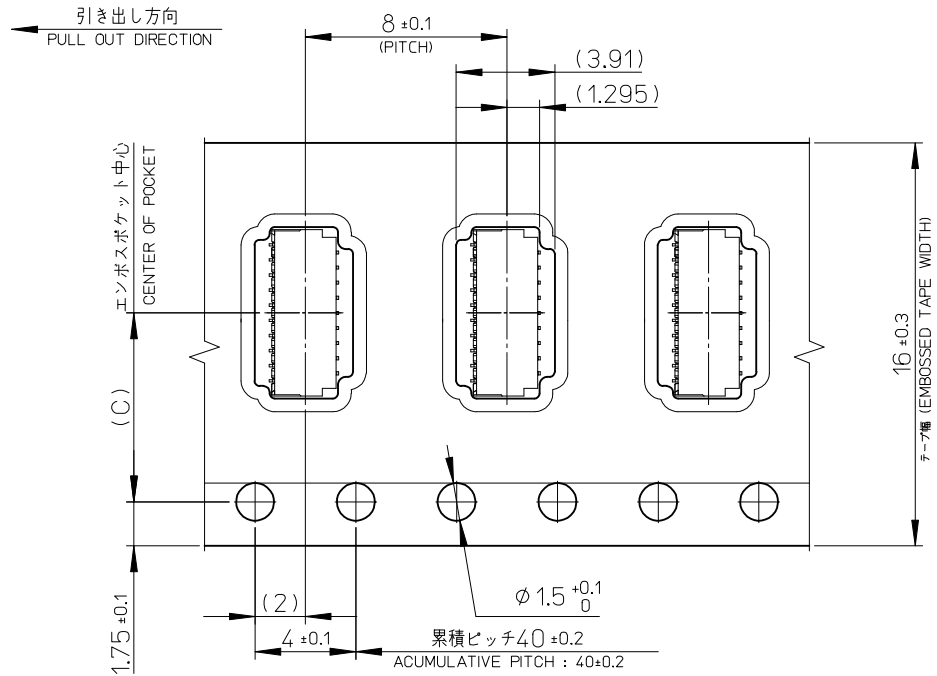


- キャリアテープ(CARRIER TAPE) : ポリスチレン(POLYSTYRENE)  
トップテープ(TOP TAPE) : PET, PE, PEF  
リール(REEL) : ポリスチレン(POLYSTYRENE) <リサイクル材を含む>  
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
- トップテープの剥離強度については、IEC60286-3に準拠  
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3



RELEASED EC NO: J2014-0037 DRWN: SKUROSE 2014/04/28 CHKD: HIJIMA 2014/04/28 APPR: YNOGAWA 2014/05/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY SKUROSE	DATE 2013/05/20	TITLE 0.3 FPC CONN NON-ZIF TYPE HGT=1.0MM	
	10 OVER 30 UNDER	±0.25	CHECKED BY HIJIMA	DATE 2013/05/20	<b>molex</b> DOCUMENT NO. SD-504281-002 SHEET NO. 1 OF 2	
	30 OVER	±0.3	APPROVED BY YNOGAWA	DATE 2014/05/07		
ANGULAR ±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART			
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1



7.5	17.4	6.6	504281-1900	19
		6.0	504281-1700	17
		4.8	504281-1300	13
		4.2	504281-1100	11
C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	種 教 CkT.

SEE SHEET 1 OF 2 EC NO: J2014-0037 DRWN:SKUROSE 2014/04/28 CHKD:H I J I M A 2014/04/28 APPR:YNOGAWA 2014/05/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY SKUROSE	DATE 2013/05/20	TITLE 0.3 FPC CONN NON-ZIF TYPE HGT=1.0MM	
	10 OVER 30 UNDER	±0.25	CHECKED BY H I I J I M A	DATE 2013/05/20	molex	
	30 OVER	±0.3	APPROVED BY YNOGAWA	DATE 2014/05/07		
	ANGULAR	±1 °	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1	SD-504281-002		2 OF 2	

SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

9 8 7 6 5 4 3 2